

Title (en)
METHOD FOR DISPOSING A CONDUCTOR STRUCTURE ON A SUBSTRATE, AND SUBSTRATE COMPRISING SAID CONDUCTOR STRUCTURE

Title (de)
VERFAHREN ZUM ANORDNEN EINER LEITUNGSSTRUKTUR AUF EINEM SUBSTRAT UND SUBSTRAT MIT DER LEITUNGSSTRUKTUR

Title (fr)
PROCEDE POUR DISPOSER UNE STRUCTURE DE PUISSANCE SUR UN SUBSTRAT ET SUBSTRAT MUNI DE LADITE STRUCTURE DE PUISSANCE

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Application
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Priority

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Abstract (en)
[origin: WO2005076679A2] The invention relates to a method for disposing a conductor structure on a substrate. Said method can be called transfer printing method, in which the following steps are carried out: a) a separable connection is created between at least one transfer support and the conductor structure; b) the transfer support comprising the conductor structure and the substrate are joined together such that a connection that is stronger than the separable connection between the transfer support and the conductor structure is created between the conductor structure and the substrate; and c) the separable connection between the transfer support and the conductor structure of the transfer support is separated while the connection between the conductor structure and the substrate remains intact. The inventive method is particularly suitable for laterally disposing conductor structures comprising nanotubes at relatively low temperatures ($T < 600$ DEG C), resulting in a substrate with a conductor structure which is connected to the substrate on a contact surface of the substrate and at least one additional contact surface of the substrate. The inventive substrate is characterized in that the conductor structure is provided with nanotubes between the two contact surfaces of the substrate, said nanotubes being oriented from the contact surface of the substrate to the additional contact surface of the substrate. The nanotubes are arranged laterally such that nanowires are created, allowing the excellent electrical and thermal properties of the nanotubes to be utilized.

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